

ABSTRACT

FILM-LIKE ADHESIVE COMPOSITE SHEET AND METHOD FOR
MANUFACTURING SEMICONDUCTOR DEVICE

5 A film-like adhesive composite sheet including:

 a support sheet having a base material; and

 a curable film-like adhesive provided on the support sheet and having a
thickness of 1 to 50 μm ,

 wherein a peel force at an interface between the support sheet and the film-like
10 adhesive is from 0.02 to 0.2 N / 25 mm, and

 the film-like adhesive has the following properties:

 a breaking elongation of a laminated body obtained by laminating the film-like
adhesive before curing so that the total thickness becomes 200 μm is equal to or less than
450%.

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FIG. 6